

## CMOS CAMERA MODULES

your BEST camera module partner

### KLT-IRSW-OV4682 V2.0 **OmniVision OV4682 with IR Switch MIPI Interface Foco Fixo 4MP M12** Módulo de Câmera

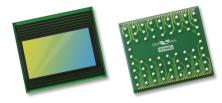


Módulo de câmara No.	KLT-IRSW-OV4682 V2.0	
Sensor de imagem	OV4682	IR SWITCH
EFL	3.1 mm	Input Voltage: 4V ~ 12V
F.NO	1.8	Operating Current: 88 ~ 300 mA
Pixel	2688 x 1520	Red Line: Positive
Ângulo de visão	140°	Black Line: Negative
Tipo de lente	1/3 polegada	
Dimensões da lente	14.00 x 14.00 x 23.10 mm	Operation:
Tamanho do Módulo	57.07 x 30.00 mm	ON: IR Active (Day Time)
Tipo de Módulo	Foco Fixo	OFF: IR Disable (Night Time)
Interface	MIPI	



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# OV4682 4MP product brief





## 0 Lux - IR Strobe

## Dual-Purpose RGB IR CameraChip<sup>™</sup> Sensor Brings High Sensitivity and High Frame Rates to Mobile and Machine Vision Applications



available in a lead-free package

OmniVision's OV4682 is a 4-megapixel RGB infrared (IR) single sensor that captures high-resolution images and video as well as IR information. Its dual RGB and IR capabilities allow it to bring a host of additional features to mobile and machine vision applications, including gesture sensing, depth analysis, iris detection and eye tracking. By combining two capabilities into a single sensor, the OV4682 reduces the total cost for the system while also reducing the space required for multiple sensors.

The sensor's 2-micron OmniBSI-2<sup>™</sup> pixel delivers excellent signal-to-noise ratio and IR sensitivity, and offers best-in-class low-light sensitivity with a 40 percent increase in sensitivity compared to the 1.75-micron OmniBSI-2 pixel. The OV4682's unique architecture and pixel optimization bring not only the best IR performance but also best-in-class image quality. Additionally, the sensor reduces system-level power consumption by optimizing RGB and IR timing.

The OV4682 records full-resolution 4-megapixel video in a native 16:9 format at 90 frames per second (fps), with a quarter of the pixels dedicated to capturing IR. The 1/3-inch sensor can also record 1080p high definition (HD) video at 120 fps with electronic image stabilization (EIS), or 720p HD at 180 fps.

The OV4682 features a high-speed 4-lane MIPI serial output interface to facilitate the required high data transfer rate. It fits into an  $8.5 \times 8.5$  mm module with a z-height of less than 6 mm.

Find out more at www.ovt.com.





#### Applications

- Cellular Phones
- Tablets
- Digital Still Cameras (DSC)
- Digital Video Camcorders (DVC)
- PC Multimedia Security
- Gaming
- Gesture Detection

#### **Product Features**

- automatic black level calibration (ABLC) support 2x2 binning, 4x4 binning,
- programmable controls for frame rate, mirror and flip, cropping, and windowing standard serial SCCB interface
- static defective pixel canceling
- supports output formats: 10-bit RAW RGB-IR (MIPI)
- supports horizontal and vertical subsampling
- supports images sizes: 4MP, 3MP, EIS1080p, 1080p, EIS720p
- fast mode switching

- re-sampling filter
- up to 4-lane MIPI serial output interface
- embedded 4K bits one-time programmable (OTP) memory for part identification, etc.
- two on-chip phase lock loops (PLLs)
- programmable I/O drive capability
- built-in temperature sensor

## **Product Specifications**

- active array size: 2688 x 1520
- power supply:
  core: 1.1 1.3V
  analog: 2.6 3.0V
  I/O: 1.7 3.0V

OV04682-G04A-1D

- power requirements: active: 163 mA (261 mW)
- -standby:1 mA - XSHUTDOWN: <10 µA
- temperature range:
  operating: -30°C to +85°C junction temperature stable image: 0°C to +60°C junction temperature
- output formats: 10-bit RAW RGB data
- lens size: 1/3"
- input clock frequency: 6 64 MHz

lens chief ray angle: 21° non-linear maximum image transfer rate: - **2688x1520**: 90 fps - **1920x1080**: 120 fps

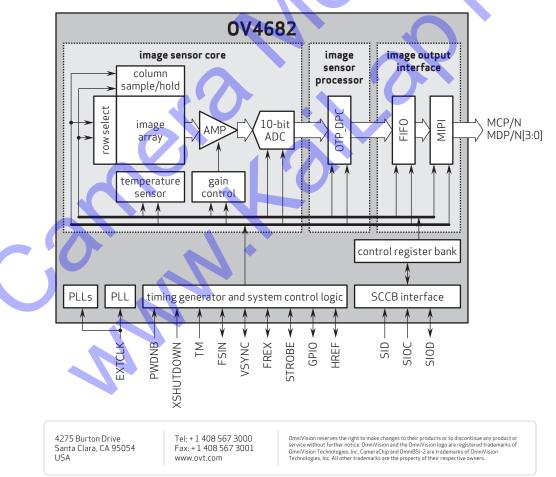
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- 1280x720: 180 fps -672x380: 330 fps

(RGB-IR, chip probing, 200 µm backgrinding, reconstructed wafer with good die)

- scan mode: progressive
- maximum exposure interval:  $1548 \times T_{ROW}$
- **pixel size:** 2 μm x 2 μm
- dark current: 4 mV/sec @ 60°C junction temperature
- **π image area:** 5440 μm x 3072 μm
- die dimensions:
   COB: 6600 μm x 5800 μm
   RW: 6650 μm x 5850 μm

## Functional Block Diagram





Version 2.2, October, 2014